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LEE et al.(10) **Pub. No.: US 2017/0027055 A1**(43) **Pub. Date: Jan. 26, 2017**(54) **FLYING TAIL TYPE RIGID-FLEXIBLE
PRINTED CIRCUIT BOARD****Publication Classification**(51) **Int. Cl.****H05K 1/02** (2006.01)**H05K 3/46** (2006.01)(52) **U.S. Cl.****CPC** **H05K 1/0278** (2013.01); **H05K 3/4652**
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(57)

ABSTRACT

The present invention relates to a method of manufacturing a flying tail type rigid-flexible printed circuit board and a flying tail type rigid-flexible printed circuit board manufactured by the same and implement a flying tail type rigid-flexible printed circuit board with improved filling property by providing a method of manufacturing a flying tail type rigid-flexible printed circuit board including: providing a base substrate having a first inner circuit pattern layer on both surfaces; laminating a first insulating layer on a rigid domain R of the base substrate; laminating at least one circuit layer, which extends over the entire domain of the base substrate, on the first insulating layer; and removing a portion of the circuit layer, which corresponds to a flexible domain F, wherein the circuit layer includes a second insulating layer and a flying tail type rigid-flexible printed circuit board manufactured by the same.

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Suwon-si (KR)(21) Appl. No.: **15/285,390**(22) Filed: **Oct. 4, 2016****Related U.S. Application Data**(63) Continuation of application No. 13/771,830, filed on
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